

LH534R00A

CMOS 4M (512K × 8) Mask-Programmable ROM

FEATURES

- 524,288 words × 8 bit organization
- Access time: 120 ns (MAX.)
- Power consumption:
 - Operating: 357.5 mW (MAX.)
 - Standby: 550 μ W (MAX.)
- Mask-programmable control pin:
 - Pin 1 – $\text{OE}_1/\overline{\text{OE}}_1/\text{DC}$
 - Pin 24 – $\text{OE}/\overline{\text{OE}}$
- Static operation
- TTL compatible I/O
- Three-state outputs
- Single +5 V power supply
- Packages:
 - 32-pin, 600-mil DIP
 - 32-pin, 525-mil SOP
 - 32-pin, 400-mil TSOP (Type II)

DESCRIPTION

The LH534R00A is a 4M-bit mask-programmable ROM organized as 524,288 × 8 bits. It is fabricated using silicon-gate CMOS process technology.

PIN CONNECTIONS

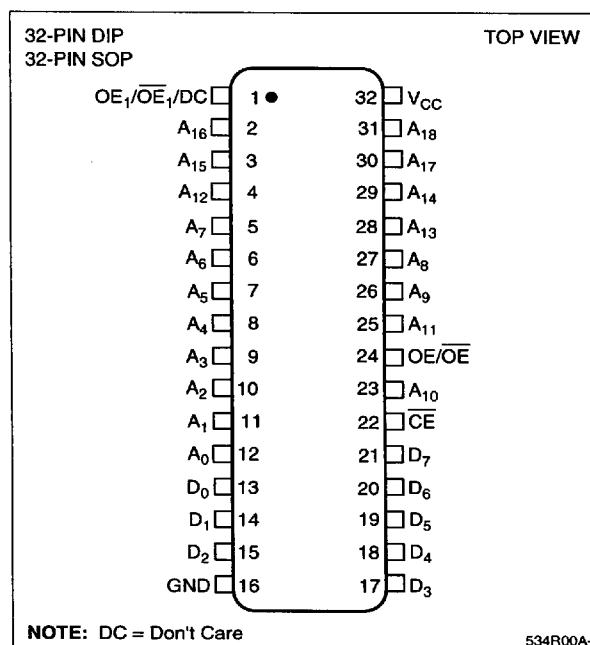


Figure 1. Pin Connections for DIP and SOP Packages

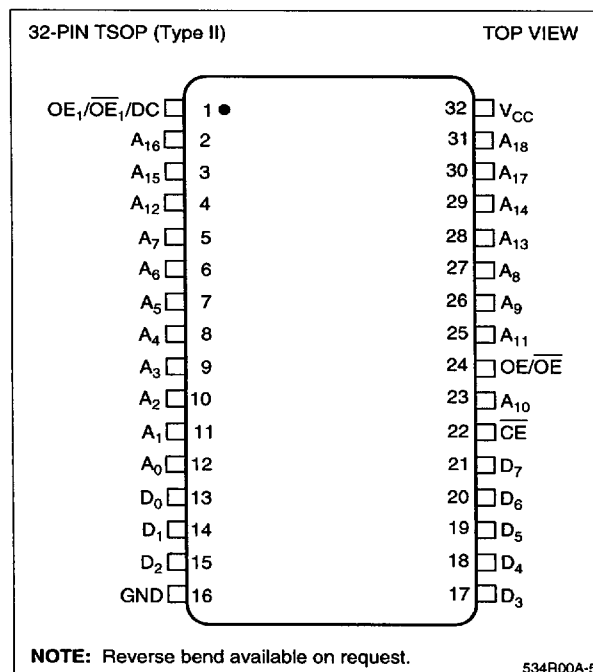


Figure 2. Pin Connections for TSOP Package

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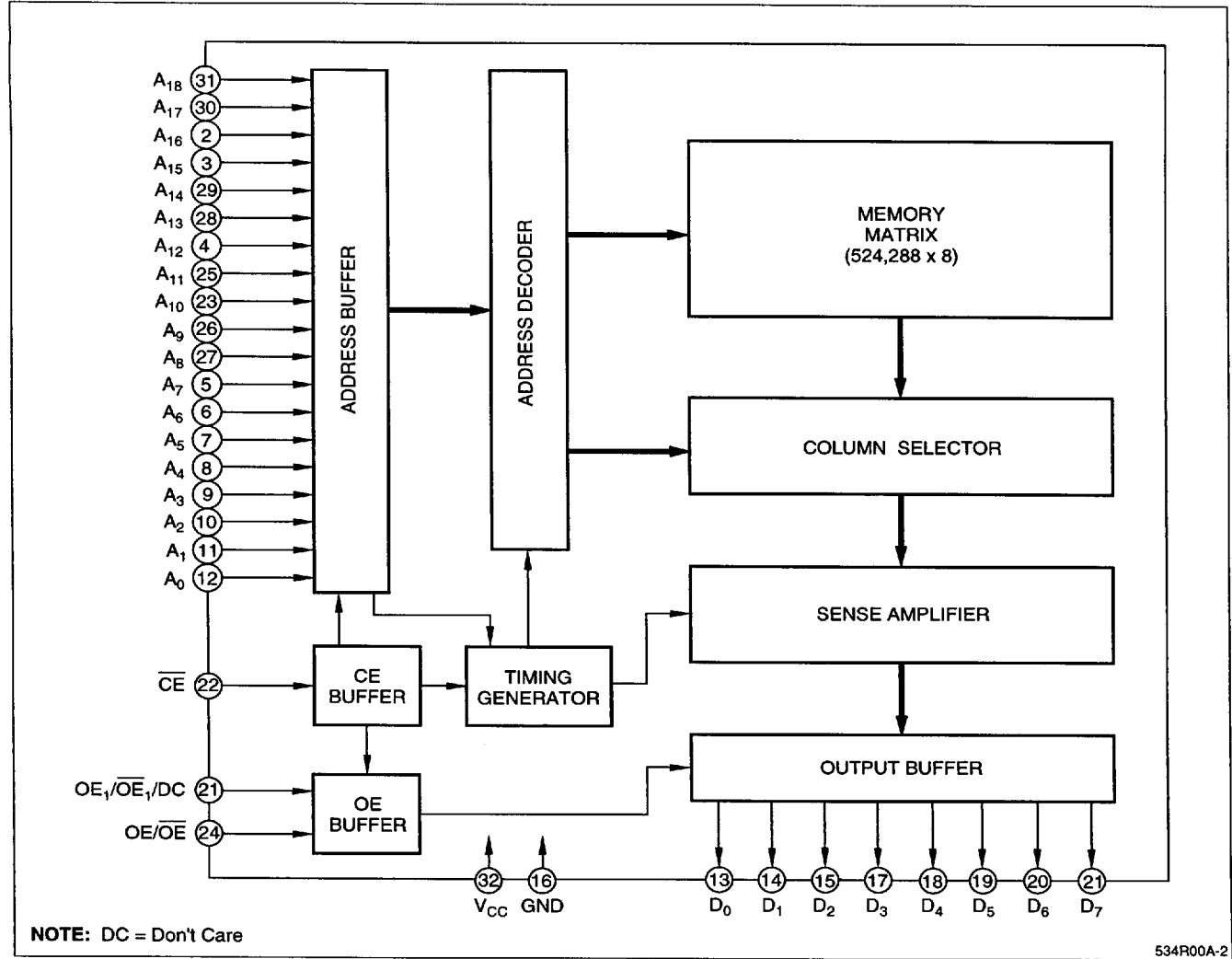


Figure 3. LH534R00A Block Diagram

PIN DESCRIPTION

SIGNAL	PIN NAME	NOTE
A ₀ – A ₁₈	Address input	
D ₀ – D ₇	Data output	
CE	Chip Enable input	
OE/OE	Output Enable input	1

SIGNAL	PIN NAME	NOTE
OE ₁ /OE ₁ /DC	Output Enable input	1, 2
V _{CC}	Power supply (+5 V)	
GND	Ground	

- NOTE:
- 1. Active levels of OE₁/OE₁/DC and OE/OE are mask-programmable. Selecting DC allows the outputs to be active for both high and low levels applied to this pin. It is recommended to apply either a HIGH or a LOW to the DC pin.
 - 2. DC = Don't care.

TRUTH TABLE

CE	OE ₁ /OE ₁	OE/OE	D ₀ – D ₇	SUPPLY CURRENT
H	X	X	High-Z	Standby (I _{SB})
L	L/H	X	High-Z	Operating (I _{CC})
L	X	L/H	High-Z	
L	H/L	H/L	Output	

NOTE:

X = H or L

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT
Supply voltage	V _{CC}	–0.3 to +7.0	V
Input voltage	V _{IN}	–0.3 to V _{CC} + 0.3	V
Output voltage	V _{OUT}	–0.3 to V _{CC} + 0.3	V
Operating temperature	T _{opr}	0 to +70	°C
Storage temperature	T _{stg}	–65 to +150	°C

RECOMMENDED OPERATING CONDITIONS (T_A = 0 to +70°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	V _{CC}	4.5	5.0	5.5	V

DC CHARACTERISTICS (V_{CC} = 5 V ±10%, T_A = 0 to +70°C)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	NOTE
Input 'Low' voltage	V _{IL}		–0.3		0.8	V	
Input 'High' voltage	V _{IH}		2.2		V _{CC} + 0.3	V	
Output 'Low' voltage	V _{OL}	I _{OL} = 2.0 mA			0.4	V	
Output 'High' voltage	V _{OH}	I _{OH} = –400 μA	2.4			V	
Input leakage current	I _{LI}	V _{IN} = 0 V to V _{CC}			10	μA	
Output leakage current	I _{LO}	V _{OUT} = 0 V to V _{CC}			10	μA	1
Operating current	I _{CC1}	t _{RC} = 120 ns			65	mA	2
	I _{CC2}	t _{RC} = 1 μs			50		
	I _{CC3}	t _{RC} = 120 ns			60	mA	3
	I _{CC4}	t _{RC} = 1 μs			45		
Standby current	I _{SB1}	CE = V _{IH}			3	mA	
	I _{SB2}	CE = V _{CC} – 0.2 V			100	μA	
Input capacitance	C _{IN}	f = 1 MHz			10	pF	
Output capacitance	C _{OUT}	T _A = 25°C			10	pF	

NOTES:

1. CE/OE/OE₁ = V_{IH}, OE/OE₁ = V_{IL}
2. V_{IN} = V_{IH} or V_{IL}, CE = V_{IL}, outputs open
3. V_{IN} = (V_{CC} – 0.2 V) or 0.2 V, CE = 0.2 V, outputs open

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AC CHARACTERISTICS ($V_{CC} = 5\text{ V} \pm 10\%$, $T_A = 0\text{ to }+70^\circ\text{C}$)

PARAMETER	SYMBOL	MIN.	MAX.	UNIT	NOTE
Read cycle time	t_{RC}	120		ns	
Address access time	t_{AA}		120	ns	
Chip enable access time	t_{ACE}		120	ns	
Output enable delay time	t_{OE}		60	ns	
Output hold time	t_{OH}	0		ns	
CE to output in High-Z	t_{CHZ}		60	ns	1
OE to output in High-Z	t_{OHZ}		60	ns	

NOTE:

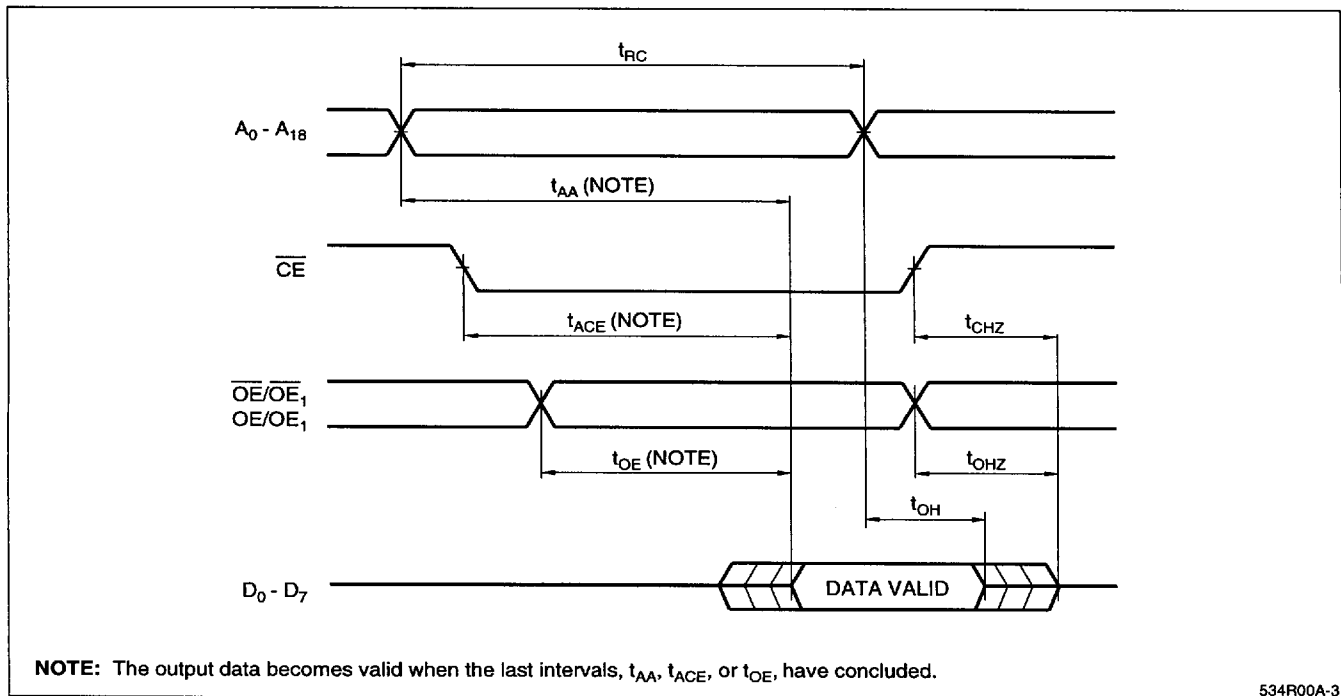
1. This is the time required for the outputs to become high-impedance.

AC TEST CONDITIONS

PARAMETER	RATING
Input voltage amplitude	0.4 V to 2.6 V
Input rise/fall time	10 ns
Input/output reference level	1.5 V
Output load condition	1TTL + 100 pF

CAUTION

To stabilize the power supply, it is recommended that a high-frequency bypass capacitor be connected between the V_{CC} pin and the GND pin.

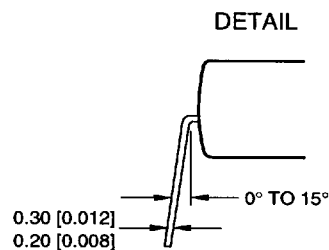
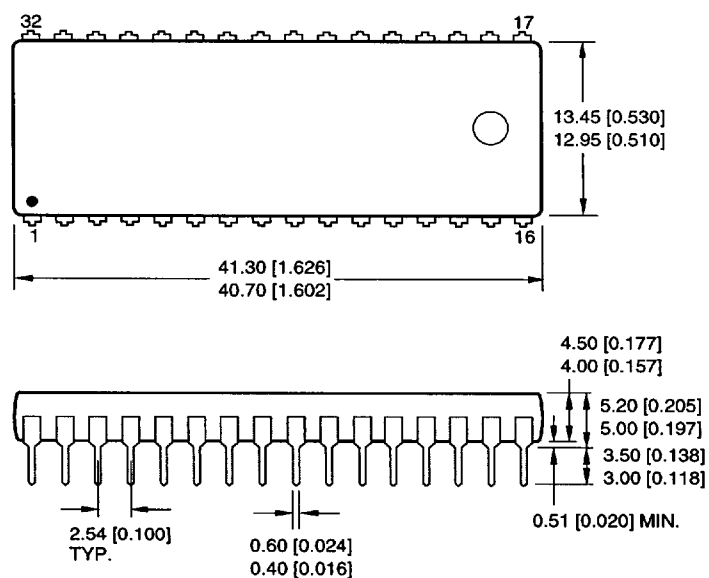


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Figure 4. Timing Diagram

PACKAGE DIAGRAMS

32DIP (DIP032-P-0600)

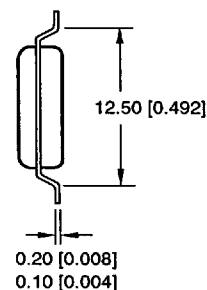
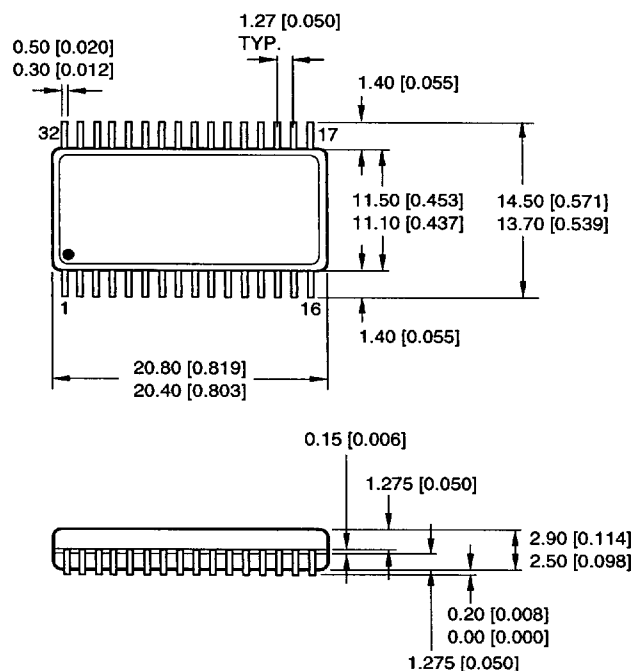


DIMENSIONS IN MM [INCHES] MAXIMUM LIMIT
MINIMUM LIMIT

32DIP

32-pin, 600-mil DIP

32SOP (SOP032-P-0525)



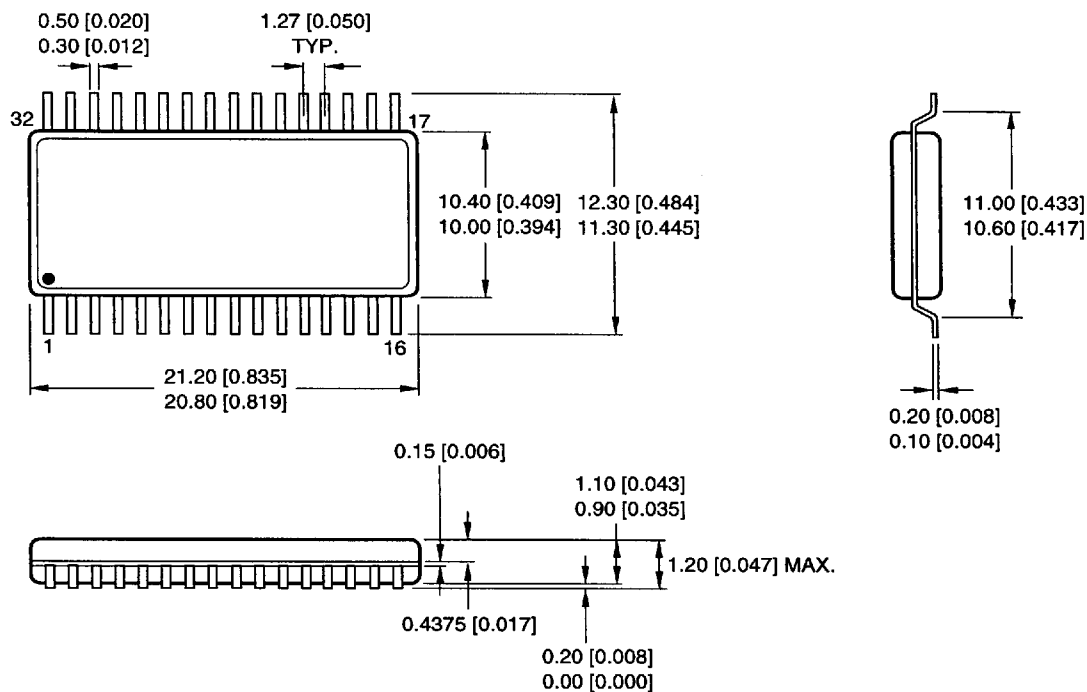
DIMENSIONS IN MM [INCHES] MAXIMUM LIMIT
MINIMUM LIMIT

32SOP

32-pin, 525-mil SOP

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32TSOP (Type II) (TSOP032-P-0400)

DIMENSIONS IN MM [INCHES] MAXIMUM LIMIT
MINIMUM LIMIT

32TSOP400

32-pin, 400-mil TSOP (Type II)**ORDERING INFORMATION**

LH534R00A
 Device Type

X
 Package

- D 32-pin, 600-mil DIP (DIP032-P-0600)
- N 32-pin, 525-mil SOP (SOP032-P-0525)
- S 32-pin, 400-mil TSOP (Type II) (TSOP032-P-0400)
- SR 32-pin, 400-mil TSOP (Type II) Reverse bend (TSOP032-P-0400)

CMOS 4M (512K x 8) Mask-Programmable ROM

Example: LH534R00AD (CMOS 4M (512K x 8) Mask-Programmable ROM, 32-pin, 600-mil DIP)

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